Ensemble® 6000 Series
OpenVPX Intel Xeon Dual Octal-Core HDS6601 Module

Extreme performance for rugged signal and data processing in a high-density server

MERCURY SYSTEMS™

- 6U OpenVPX™-compliant VITA 65/46/48 (VPX-REDI) module
- Two octal-core Sandy Bridge server-class Intel® processors provide 16 cores at 1.8 GHz
- Total of 460 GFLOPS peak in a single slot
- Serial RapidIO® and/or 10 Gigabit Ethernet fabric enabled
- 32 GB of DDR3-1600 SDRAM with 102 GB/s peak performance
- Integrated PCIe® infrastructure for co-processing and I/O expansion plane communications
- Mercury MultiCore Plus® software infrastructure support

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The Ensemble® HDS6601 is a high-density server signal and data processing engine, harnessing two of the latest generation of server-class Sandy Bridge octal-core Intel® Xeon® processors for the most demanding applications. The HDS6601 combines this processing performance with a next-generation Protocol Offload Engine Technology (POET™) fabric bridge, scaling the module's I/O infrastructure to match the unparalleled embedded processing performance of server-class Intel processors.

By leveraging the power of Intel server-class processing in combination with the on-board integrated high-performance PCIe® and fabric infrastructure, the HDS6601 delivers a well-balanced and scalable computing architecture. The HDS6601 is capable of providing ground-breaking levels of processing power for high-end radar, signal intelligence and image processing applications, as well as data-intensive commercial applications, in a standard 6U OpenVPX™ form factor.

Intel Xeon Sandy Bridge Server-Class Processor

The HDS6601 features two 64-bit Xeon E5-2648LE Sandy Bridge–class octal core processors. Following on technology first deployed on the HDS6600, the HDS6601 utilizes unique packaging technologies to support two instances of 2011-pin Land Grid Array (LGA) processors in a rugged, embedded form factor. The dual octal-core processors are linked via two instances of the high-speed, low-latency QPI interface, each of which provides a 25.6 GB/s transfer rate, for a staggering total of 51.2 GB/s of bandwidth between processors.

This interconnected processor architecture is optimized for the intense data movement needed by processing algorithms, such as all-to-all corner turn operations. From a software perspective, this QPI architecture allows the HDS6601 to be configured with a single kernel NUMA-aware operating system running across both processor devices. Each processor is capable of delivering approximately 230 GFLOPS (peak), with four high-speed DDR3-1600 memory channels capable of 12.8 GB/s raw bandwidth each, for an incredible total peak of 460 GFLOPS and 102.4 GB/s total raw memory bandwidth.

The HDS6601 refines the innovative standing memory technology first seen on the HDS6600 to support 32 GB of DRAM on-board for the ultimate in DRAM density in the OpenVPX family of processing modules. Native PCIe support is also featured on this processor, linking the processing resources directly to the I/O sources on the module. The HDS6601 also makes use of the Patsburg-B Platform Controller Hub (PCH) chipset, which provides additional I/O bridging between the Intel processor and external devices.

Mercury Systems is a best-of-breed provider of commercially developed, open sensor and Big Data processing systems, software and services for critical commercial, defense and intelligence applications.

ACQUIRE   DIGITIZE   PROCESS   STORAGE   EXPLOIT   DISSEMINATE

The E5-2648L processor includes a very large 20MB cache, shared between the cores, allowing many high-performance calculations to remain cache resident. This accelerates processing by eliminating the potential latency required to access DRAM to fetch upcoming data. The Sandy Bridge family of processors also supports the newly introduced AVX instruction set, delivering a revolutionary increase in floating-point high-performance algorithm performance that is portable to future Intel architectures.

High-Speed Fabric Interfaces

The HDS6601 continues the Mercury Systems tradition of combining the processing power of Intel processors with a high-speed Serial RapidIO® or 10 Gigabit Ethernet fabric interface. The on-board Virtex® 6 FPGA can be configured with IP that provides a streaming bridge for high-bandwidth, low-latency data. The HDS6601 supports either Serial RapidIO (Gen2) or 10 Gigabit Ethernet bridging to the native PCIe interface on the Intel processor. The HDS6601 improves on previous generations in the HDS family by providing a full complement of four x4 data plane interfaces to the backplane. By linking the Intel processor with a high-performance OpenVPX™ data plane, the HDS6601 architecture ensures an optimal balance between I/O and processing capabilities.

PCI Express Architecture

The HDS6601 provides high-end PCe backplane interfaces via the native PCIe resources on the E5-2648L processor. In addition to supporting the processor's interface to the POET bridge described earlier, an additional x16 PCIe interface is provided to the OpenVPX expansion plane interface on both the P2 and P5 VPX connectors. These interfaces enable the HDS6601's compatibility with Mercury's GPU, FPGA or mezzanine carrier modules. The interfaces are user configurable to lower port widths. These configuration options support the construction of complex PCIe trees with many other PCIe-capable devices.

Multiple I/O Options

The HDS6601 offers a variety of additional built-in I/O options:
- One 10/100/1000BASE-T Gigabit Ethernet connection routed to the front panel on air-cooled configurations or to the backplane on conduction-cooled configurations.
- One additional 10/100/1000BASE-T Gigabit Ethernet connection routed to the backplane.
- Two 1000BASE-BX SERDES Ethernet connections routed to the backplane as per the OpenVPX control plane specification.
- One RS-232 serial port is routed to the front panel on air-cooled configurations, or to the backplane on conduction-cooled configurations. When routed to the backplane, the serial interface can be configured for either RS-232 or RS-422 signaling.
- One additional RS-422 interface and two RS-232 interfaces are routed to the backplane.

- One front panel USB2.0 interface on air cooled configurations only.
- Two backplane USB2.0 interfaces, available with both air-cooled and conduction-cooled configurations.
- One front panel eSATA interface on air-cooled configurations only.
- Two SATA interfaces to the backplane are provided to easily interface with storage devices.
- Eight GPIO lines act as discrete I/O, usable as input, output or to generate interrupts on the module.
- Several additional bused signals that enhance the functionality of the HDS6601 module.

System Management

The HDS6601 module implements the advanced system management functionality architected in the OpenVPX Specification to enable remote monitoring, alarm management and hardware revision and health status.

Using the standard I2C bus and Intelligent Platform Management Interface (IPMI) protocol, the on-board system management block implements the Intelligent Platform Management Controller (IPMC), in accordance with the VITA 46.11 standard. This allows the HDS6601 module to:
- Read sensor values
- Read and write sensor thresholds, allowing an application to react to thermal, voltage or current variations that exceed those thresholds
- Reset the entire module
- Power up/down the entire module
- Retrieve module Feld Replaceable Unit (FRU) information
- Be managed remotely by a Chassis Management Controller at the system level, such as implemented on the OpenVPX™ SFM6101 and SFM6102 series of Switch Fabric Modules

VPX-REDI

The VPX™ (VITA 46) standard defines 6U and 3U board formats with a modern high-performance connector set capable of supporting today's high-speed fabric interfaces. VPX is most attractive when paired with the Ruggedized Enhanced Design Implementation standard — REDI (VITA 48). The HDS6601 module is implemented as a 6U conduction-cooled implementation of VPX-REDI, with air-cooled variants in the same VPX form factor available for less rugged environments. Targeted primarily for harsh-environment embedded applications, VPX-REDI offers extended mechanical configurations supporting higher functional density, such as Two-Level Maintenance (2LM). 2LM allows relatively unskilled maintenance personnel to replace a failed module and restore the system to an operational state in a limited time period, minimizing potential damage to the module.
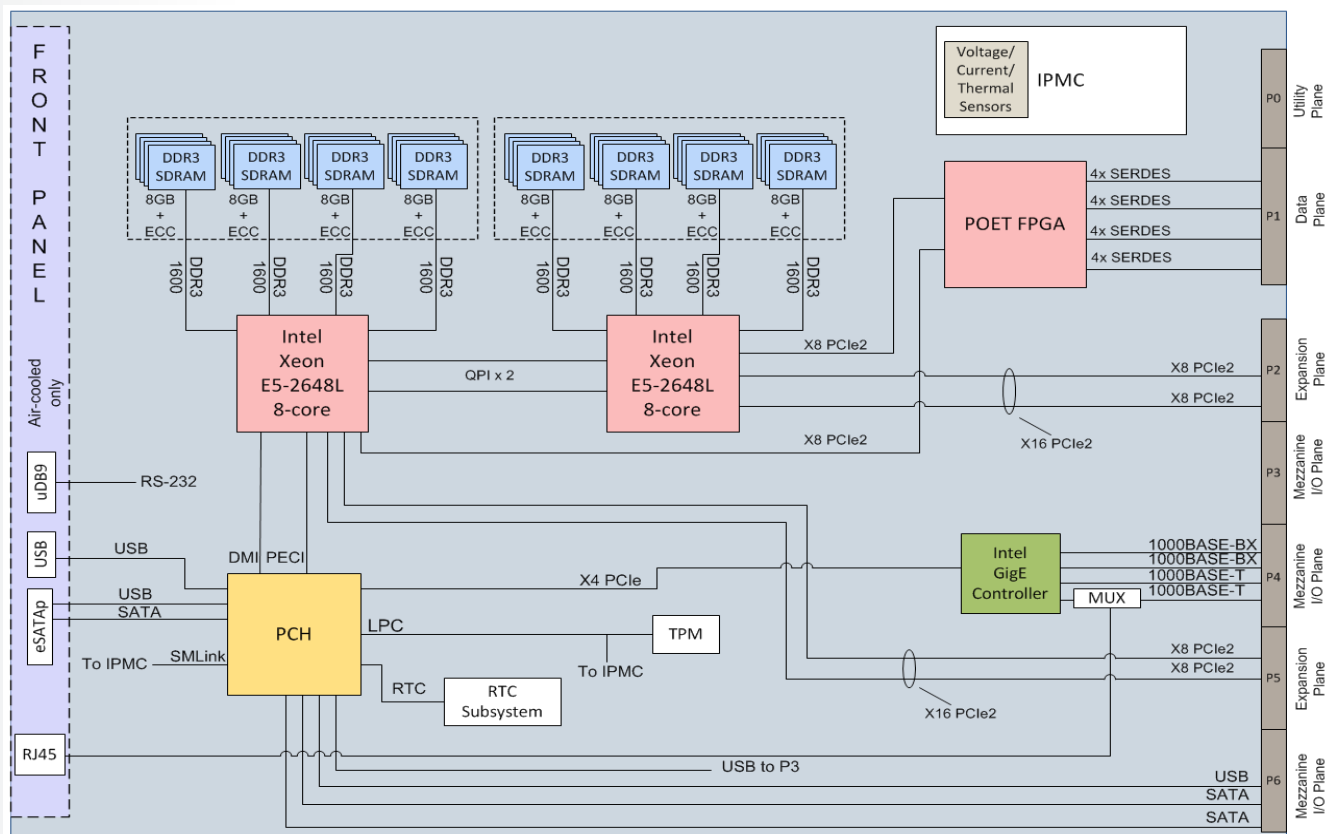
Figure 1. *HDS6601 functional block diagram*

Additional Features

The HDS6601 provides all the features typically found on a single-board computer. In addition to the sophisticated management subsystem and fabric interconnect, it provides users with a toolkit enabling many different application use cases.

Features include:

- Thermal and voltage sensors integrated on-board
- Real-time clock with granularity to 1 ms and time measurement of up to 30 years
- General-purpose timers
- Global clock synchronization capabilities via the OpenVPX utility plane clock signals
- Watchdog timer to support interrupt or reset
- Multiple boot paths, including netboot, USB boot, and boot from SATA or the on-board 8 GB flash device

Open Software Environment

Mercury leverages over 25 years of multicomputer software expertise, including recent multicore processor expertise, across its many platforms. This strategy is fully applied to the HDS6601 module. Because the processor, memory and surrounding technologies are leveraged across product lines, software developed on the HDS6601 module can interface seamlessly with other Mercury products. The same development and run-time environment is implemented on the HDS6601 module as on other Mercury platforms across the Ensemble 3000, 5000 and 6000 series.

The MultiCore Plus (MCP) open software environment gives the HDS6601 module access to a wide ecosystem of stacks, middleware, libraries and tools. Software support is available on the HDS6601 module for the following products:

Support for Mercury's standard numeric libraries via the MathPak product, which includes Vector Signal Image Processing Library (VSIPL) and Scientific Algorithm Library (SAL), is optimized for the Intel AVX architecture of the HDS6601 module.

Open Development Suite for Linux® is an Eclipse-based integrated development environment that includes a C/C++ optimizing compiler, a source-level debugger, a language-sensitive text editor, a performance profiler, a project builder, a version control system, a run-time error checker and a graphical source browser. Mercury provides extensions that allow multiprocessor-aware process launch and debug, as well as a System Supervisor view that allows graphical remote management.

Support is provided for Wind River® Workbench integrated development environment when the module is running Wind River Linux or VxWorks®.

Interprocessor Communication System (ICS) support is carried for-ward from the RACE++®/MCOE™ software environment. ICS provides a low-level interprocessor communication API that lets users take advantage of the high-bandwidth, low-latency Serial RapidIO fabric with an easy-to-use software interface.

OpenMPI/OFED middleware support pairs an open, recognized software interface with Mercury's optimization at the fabric level for unparalleled performance for data transfers over the data plane fabric.

- Trace Analysis Tool and Library (TATL™) is a 'logic analyzer for software' that provides insight into the dynamic interaction of up to a few hundred processors.

The MCP software environment lets applications use industry-standard middleware such as MPI, DRI, CORBA or standard TCP/IP sockets ported to run seamlessly over the fabric. MCP also offers a software tool that can help migrate legacy applications created with MCOE™ into the MCP domain.

Open Standards Mean Interoperability and Planning for the Future

The OpenVPX Industry Working Group was an industry initiative launched by defense prime contractors and Commercial-Off-The-Shelf (COTS) system developers to take a proactive approach to solving the interoperability issues associated with the VITA 46 (VPX) fam-ily of specifications. This group has created an overarching System Specification defining VPX system architecture through pinout definitions to establish a limited set of application-specific reference solutions. These OpenVPX standard solutions provide clear design guidance to COTS suppliers and the user community, assuring interoperability across multi-vendor implementations. The OpenVPX System Specifications were ratified by the VSO in February 2010.

Specifications

Intel 32-nm Sandy Bridge–Class Processor

Two Octal-core E5-2648L Sandy Bridge server-class processors at 1.8 GHz each
    Peak performance 460 GFLOPS
    Threads per core 2
QPI interface between processors 2 x 25.6 GB/s peak performance
Intel Virtualization Technology
Dual Integrated x16 Gen2 PCIe interface
DDR3-1600   32 GB with ECC
Raw memory bandwidth   102 GB/s
BIOS SPI flash   Dual 8 MB partitions
NAND flash   8 GB, SATA interface

Virtex® 6 HX380T Field-Programmable Gate Array (FPGA)

Provides fabric bridging to data plane
Can act as co-processor executing iFFT/FFT, image or signal processing
Configured from CPU or dedicated configuration ROM

Ethernet Connections

1000BASE-BX Ethernet to P4 connector   2
    OpenVPX™ Control Plane
10/100/1000BASE-T Ethernet to P4 connector   1
    Accessible via OpenVPX RTM or external chassis interface
10/100/1000BASE-T Ethernet connection   1
    to front panel (air-cooled module), or
    to backplane (conduction-cooled module)
Ethernet functions supported by the chipset include:
    UDP, TCP, SCTP, ARP, IPv4, IPv6, IEEE1588, flow control, 802.1P (priority), 802.1Q (VLAN)

Intelligent Platform Management Interface (IPMI)

On-board IPMI controller
Voltage and temperature monitor
Geographical address monitor
Power/reset control
FRU and on-board EEPROM interfaces
FPGA, CPU and CPLD interfaces

OpenVPX Multi-Plane Architecture

System Management via IPMB-A and IPMB-B link on P0 management plane
Dual 4x Serial RapidIO or 10 Gigabit Ethernet interfaces on P1 data plane
Dual full x16 or dual x8 PCIe expansion plane
Dual 1000BASE-BX Ethernet control plane

Additional I/O Capabilities

RS-232 serial interface   1
    to front panel (air-cooled), or
    to backplane (conduction-cooled)
Configurable for RS-422 signaling when routed to backplane
RS-422 serial interface to backplane   1
RS-232 serial interfaces to backplane   2
Front-panel USB 2.0 interface   1
    (air-cooled configurations only)
USB 2.0 interfaces to backplane   2
Front-panel eSATA interface   1
    (air-cooled configurations only)
SATA interfaces to backplane   2
Single-ended GPIO interfaces to backplane   8
System signals to backplane
NVMRO, ChassisTest, Environmental Bypass, MemoryClear

Mechanical

6U OpenVPX (air-cooled and conduction-cooled)
1.0″ slot pitch
OpenVPX and VPX REDI

Environmental	Environmental Qualification Levels				
	Air-cooled			Air Flow-By	Conduction-cooled
	Commercial L0	Rugged L1	Rugged L2	Rugged L4	Rugged L3
Ruggedness	•	••	••	•••	•••
Moisture/dust protection	•	••	••	•••	•••
Typical cooling performance	~140W*	~140W*	~150W*	~200W*	~150W**
Temperature Operating*	0ºC to +40ºC	-25ºC to +55ºC	-45ºC to +70ºC	-40ºC to +60ºC	-40ºC to +71ºC
Operating temperature maximum rate of change	N/A	5ºC/min	10ºC/min	10ºC/min	10ºC/min
Temperature Storage	-40ºC to +85ºC	-55ºC to +85ºC	-55ºC to +125ºC	-55ºC to +125ºC	-55ºC to +125ºC
Humidity Operating*	10-90%, non-condensing	5-95%, non-condensing	5-95%, non-condensing	5-95%, non-condensing 100% condensing	5-95%, non-condensing 100% condensing
Humidity Storage	10-90%, non-condensing	5-95%, non-condensing	5-95%, non-condensing	5-95%, non-condensing 100% condensing	5-95%, non-condensing 100% condensing
Altitude Operating*	0-10,000ft	0-30,000ft	0-30,000ft	0-30,000ft	0-70,000ft
Altitude Storage	0-30,000ft	0-50,000ft	0-70,000ft	0-70,000ft	0-70,000ft
Vibration Random	0.003 g^2/Hz; 20-2000 Hz, 1 hr/axis	0.04 g^2/Hz; 20-2000 Hz, 1 hr/axis	0.04 g^2/Hz; 20-2000 Hz, 1 hr/axis	0.1 g^2/Hz; 5-2000 Hz, 1 hr/axis	0.1 g^2/Hz; 5-2000 Hz, 1 hr/axis
Vibration Sine	N/A	N/A	N/A	10G peak; 5-2000 Hz, 1 hr/axis	10G peak; 5-2000 Hz, 1 hr/axis
Vibration Shock	z-axis: 20g; x and y-axes: 32g; (11ms ½-sine pulse, 3 positive, 3 negative)	z-axis: 50g; x and y-axes: 80g; (11ms 1/2-sine pulse, 3 positive, 3 negative)	z-axis: 50g; x and y-axes: 80g; (11ms 1/2-sine pulse, 3 positive, 3 negative)	z-axis: 50g; x and y-axes: 80g; (11ms 1/2-sine pulse, 3 positive, 3 negative)	z-axis: 50g; x and y-axes: 80g; (11ms 1/2-sine pulse, 3 positive, 3 negative)
Salt/Fog	N/A	Contact Factory	Contact Factory	10% NaCl	10% NaCl
VITA 47	Contact Factory				

* Customer must maintain required cfm level. Consult factory for the required flow rates.

** Card edge should be maintained below 71ºC

Storage Temperature is defined per MIL-STD-810F, Method 502.4, para 4.5.2, where the product under non-operational test is brought to an initial high temperature cycle to remove moisture. Then the unit under non-operational test will be brought to the low storage temperature. The low temperature test is maintained for 2 hours. The product is then brought to the high storage temperature and is maintained for 2 hours. The product is then brought back to ambient temperature. All temperature transitions are at a maximum rate of 10ºC/min. One cold/hot cycle constitutes the complete non-operational storage temperature test. This assumes that the board level products are individually packaged in accordance with ASTM-D-3951 approved storage containers. These tests are not performed in Mercury shipping containers, but in an unrestrained condition. Please consult the factory if you would like additional test details.

All products manufactured by Mercury meet elements of the following specifications: MIL-STD-454, MIL-STD-883, MIL-HDBK-217F, and MIL-I-46058 or IPC-CC-830, and various IPC standards. Mercury's inspection system has been certified in accordance with MIL-I-45208A.

Additional Services	
Optional Environmental Screening and Analysis Services	Standard Module, Optional Services
• Cold Start Testing • Safety Margin Analysis • Cold Soak Testing • Temperature Cycling • Custom Vibration • Power Cycling • CFD Thermal Analysis • Environmental Stress Screening • Finite Element Analysis	• Engineering Change Order (ECO) Notification • Alternate Mean Time Between Failure (MTBF) Calculations • ECO Control • Hazmat Analysis • Custom Certificate of Conformity (CofC) • Diminished Manufacturing Sources (DMS) Management • Custom UID Labeling • Longevity of Suppy (LOS) • Longevity of Repair (LOR)
Contact factory for additional information	

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